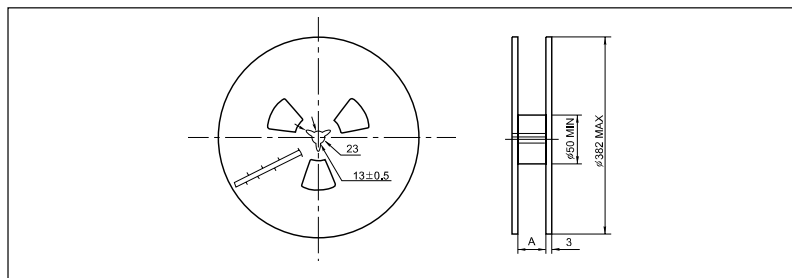


PACKAGING & REFLOW SOLDERING SPECIFICATIONS OF CHIP CAPACITORS

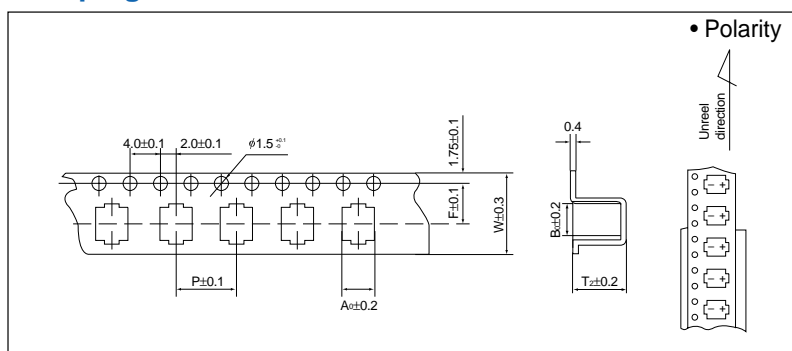
Taping Reel



Case size	A	Q'ty(Pcs/1Reel)
4 x 5.3l	14	2000
5 x 5.3l	14	1000
6 x 5.3l	18	1000
6 x 5.7l	18	1000
6 x 7.7l	18	900
8 x 6.3l	18	1000
8 x 10.0l	26	500
10 x 10.0l	26	500

Guide

Taping Dimensions in mm



Recommended Land Size



Case size	W	P	F	A ₀	B ₀	T ₂
4 x 5.3l	12.0	8.0	5.5	4.8	4.8	5.8
5 x 5.3l	12.0	12.0	5.5	6.0	6.0	5.8
6 x 5.3l	16.0	12.0	7.5	7.0	7.0	5.8
6 x 5.7l	16.0	12.0	7.5	7.0	7.0	6.3
6 x 7.7l	16.0	12.0	7.5	7.0	7.0	8.2
8 x 6.3l	16.0	12.0	7.5	8.7	8.7	6.8
8 x 10.0l	24.0	16.0	11.5	8.7	8.7	11.0
10 x 10.0l	24.0	16.0	11.5	10.7	10.7	11.0

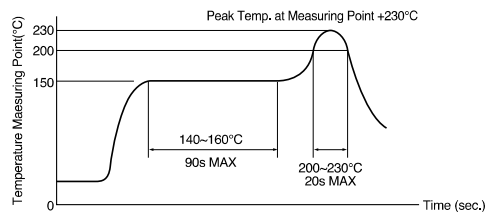
Case size	X	Y	Z
4 x 5.3l	1.6	2.6	1.0
5 x 5.3l	1.6	3.0	1.5
6 x 5.3l	1.6	3.5	2.0
6 x 5.7l	1.6	3.5	2.0
6 x 7.7l	1.6	3.5	2.0
8 x 6.3l	2.5	4.0	2.3
8 x 10.0l	2.5	3.5	3.1
10 x 10.0l	2.5	4.0	4.5

Reflow soldering

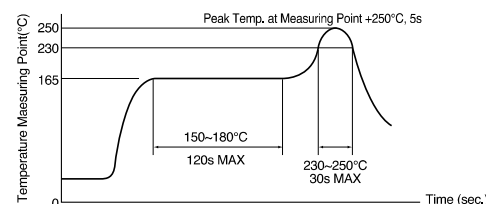
- (1) For reflow, use a thermal conduction system such as infrared radiation or hot plate
- (2) Observe proper soldering conditions (temperature, time etc.,). Do not exceed the specified limits.
- (3) Reflow should be performed one time.

Method	Allowable range of reflow
Hot-plate reflow	
Infrared-ray reflow Air reflow	

Chip Type Aluminum Electrolytic Capacitors (Conventional product)

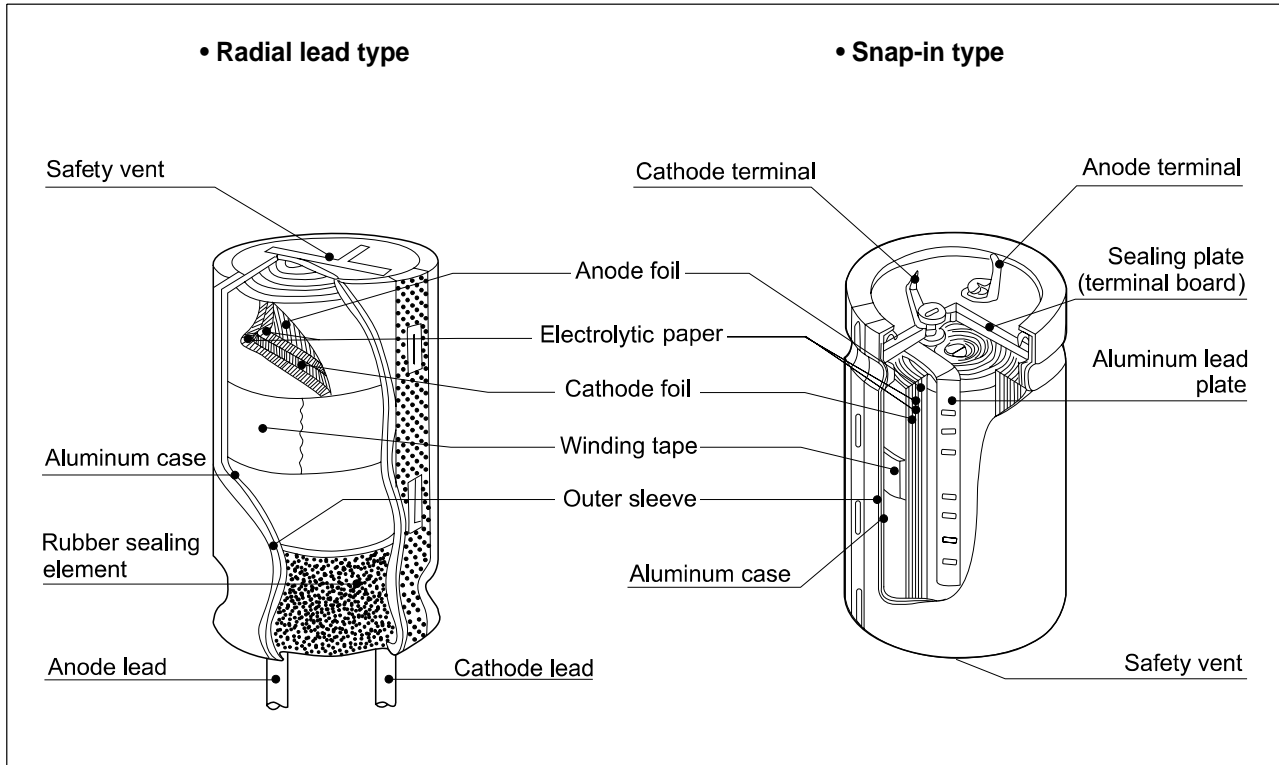


Chip Type Aluminum Electrolytic Capacitors (Lead-Free product)



MINI GLOSSARY

- Construction



Guide

